



# 4-Channel 1-Wire LED Driver in 3 x 3mm Package

## FEATURES

- Drives up to 4 LED channels
- 1-wire EZDim™ Programmable LED Current
- Accurate 1mA Dimming Level
- Power efficiency up to 91%
- Fractional pump 1x/1.5x
- Low noise input ripple
- Fixed High Frequency Operation 1MHz
- “Zero” Current Shutdown Mode
- Soft start and current limiting
- Short circuit protection
- Thermal shutdown protection
- TDFN 12-pad 3mm x 3mm package

## APPLICATIONS

- LCD Display Backlight
- Cellular Phones
- Digital Still Cameras
- Handheld Devices

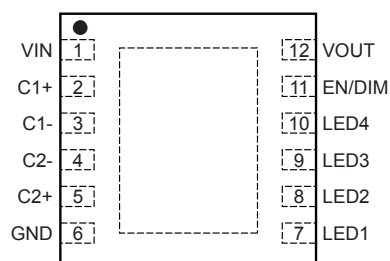
## ORDERING INFORMATION

Part Number	Package	Quantity per Reel	Package Marking
CAT3614HV2-T2	TDFN-12 <sup>(1)</sup>	2000	HAAA
CAT3614HV2-GT2	TDFN-12 <sup>(2)</sup>	2000	HAAC

**Notes:** (1) Matte-Tin Plated Finish (RoHS-compliant).  
(2) NiPdAu Plated Finish (RoHS-compliant).

## PIN CONFIGURATION

**TDFN 12-Pad 3 x 3mm  
(Top View)**



## DESCRIPTION

The CAT3614 is a high efficiency 1x/1.5x fractional charge pump with programmable dimming current in four LED channels. To ensure uniform brightness in LCD backlight applications, each LED channel delivers an accurate regulated current.

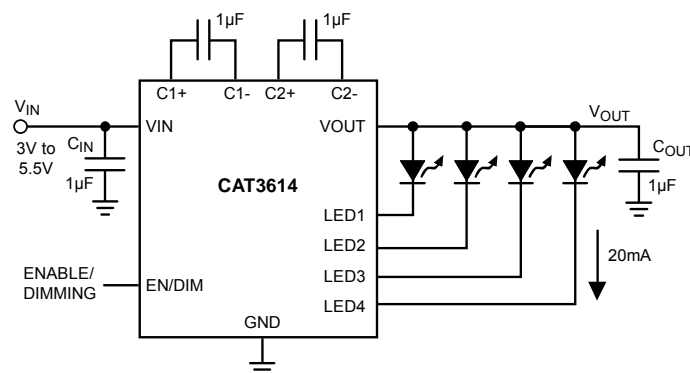
Low noise and input ripple is achieved by operating at a constant switching frequency of 1MHz which allows the use of small external ceramic capacitors. The 1x/1.5x fractional charge pump supports a wide range of input voltages from 3V to 5.5V with efficiency up to 91%, and is ideal for Li-Ion battery powered devices.

The EN/DIM logic input provides a 1-wire EZDim™ interface for dimming control of the LEDs. When enabled, a series of clock pulses reduces the LED brightness in 1mA steps on each negative going edge. Currents from 0mA to 31mA are supported.

The device is available in the tiny 12-pad TDFN 3 x 3mm package with a max height of 0.8mm.

For Ordering Information details, see page 12.

## TYPICAL APPLICATION CIRCUIT



**Note:** Unused LED channels must be connected to VOUT.

## ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Unit
V <sub>IN</sub> , LEDx voltage	6	V
V <sub>OUT</sub> , C1±, C2± voltage	7	V
EN/DIM voltage	V <sub>IN</sub> + 0.7V	V
Storage Temperature Range	-65 to +160	°C
Junction Temperature Range	-40 to +150	°C
Lead Temperature	300	°C

## RECOMMENDED OPERATING CONDITIONS

Parameter	Range	Unit
V <sub>IN</sub>	3 to 5.5	V
Ambient Temperature Range	-40 to +85	°C
I <sub>LED</sub> per LED pin	0 to 31	mA
Total Output Current	0 to 124	mA

Typical application circuit with external components is shown on page 1.

## ELECTRICAL OPERATING CHARACTERISTICS

V<sub>IN</sub> = 3.6V, EN = High, ambient temperature of 25°C (over recommended operating conditions unless specified otherwise).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>Q</sub>	Quiescent Current	1x mode, no load 1.5x mode, no load	0.3 1	0.5 3	1 8	mA mA
I <sub>QSHDN</sub>	Shutdown Current	V <sub>EN</sub> = 0V			1	µA
I <sub>LED-ACC</sub>	LED Current Accuracy	1mA ≤ I <sub>LED</sub> ≤ 31mA		±3	±8	%
I <sub>LED-DEV</sub>	LED Channel Matching	(I <sub>LED</sub> - I <sub>LEDAVG</sub> ) / I <sub>LEDAVG</sub>		±3	±7	%
R <sub>OUT</sub>	Output Resistance (open loop)	1x mode, I <sub>OUT</sub> = 100mA 1.5x mode, I <sub>OUT</sub> = 100mA		0.4 2.6	1 7	Ω Ω
F <sub>OSC</sub>	Charge Pump Frequency		0.8	1	1.3	MHz
I <sub>SC_MAX</sub>	Output short circuit Current Limit	V <sub>OUT</sub> < 0.5V	30	60	100	mA
I <sub>IN_MAX</sub>	Input Current Limit	1x mode, V <sub>OUT</sub> > 1V	200	300	600	mA
I <sub>EN/DIM</sub> V <sub>HI</sub> V <sub>LO</sub>	EN/DIM Pin • Input Leakage • Logic High Level • Logic Low Level		-1 1.3		1 0.4	µA V V
T <sub>SD</sub>	Thermal Shutdown		145	165	175	°C
T <sub>HYS</sub>	Thermal Hysteresis		10	20	30	°C
V <sub>UVLO</sub>	Undervoltage lock out (UVLO) threshold		1.7	2	2.4	V

## RECOMMENDED EN/DIM TIMING

For  $3V \leq V_{IN} \leq 5.5V$ , over full ambient temperature range  $-40$  to  $+85^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{SETP}$	EN/DIM setup from shutdown		10			$\mu s$
$T_{LO}$	EN/DIM program low time		0.3		200	$\mu s$
$T_{HI}$	EN/DIM program high time		0.3			$\mu s$
$T_{OFF}$	EN/DIM low time to shutdown		1.5			ms
$T_D$	LED current enable			40		$\mu s$
$T_{DEC}$	LED current decrement			0.1		$\mu s$

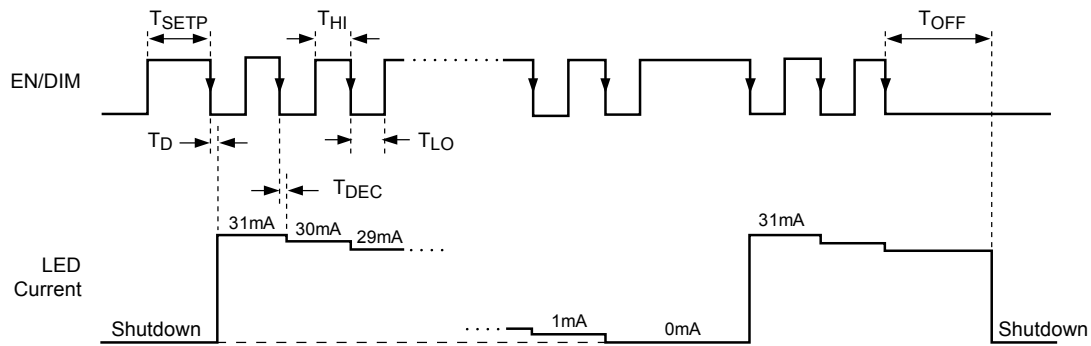
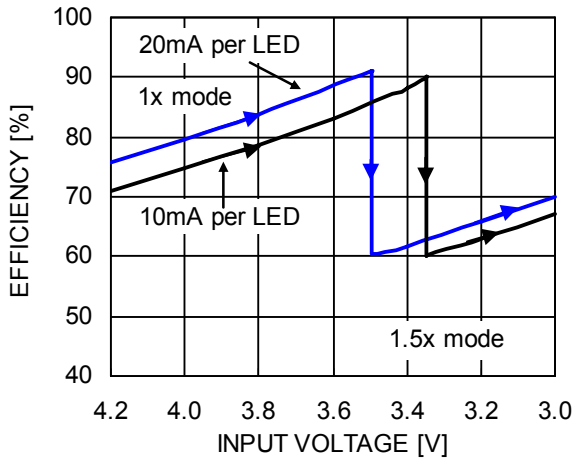


Figure 1. LED Dimming Timing Diagram

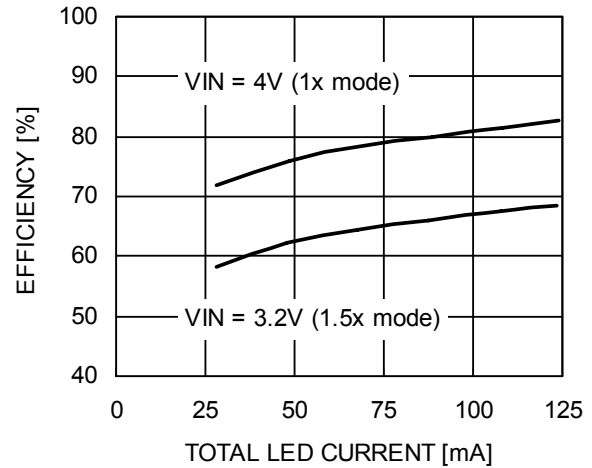
## TYPICAL CHARACTERISTICS

$V_{IN} = 3.6V$ ,  $I_{OUT} = 80mA$  (4 LEDs at 20mA),  $C_1 = C_2 = C_{IN} = C_{OUT} = 1\mu F$ ,  $T_{AMB} = 25^\circ C$  unless otherwise specified.

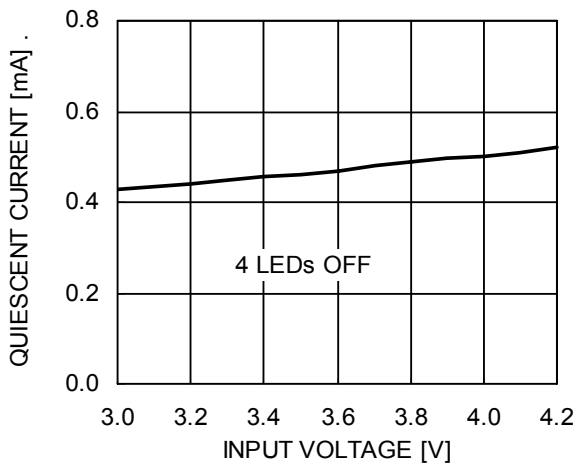
**Efficiency vs. Input Voltage (4 LEDs)**



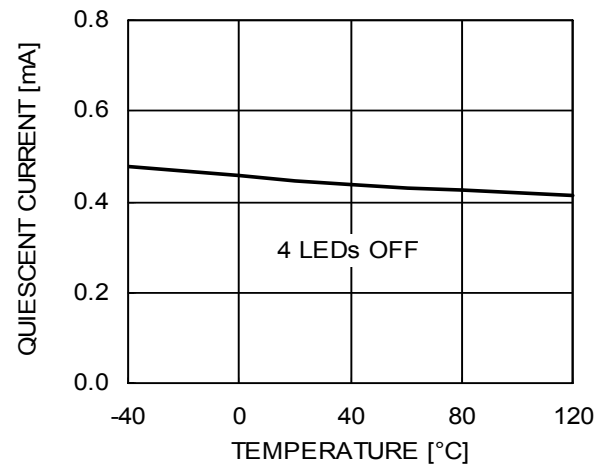
**Efficiency vs. Total LED Current (4 LEDs)**



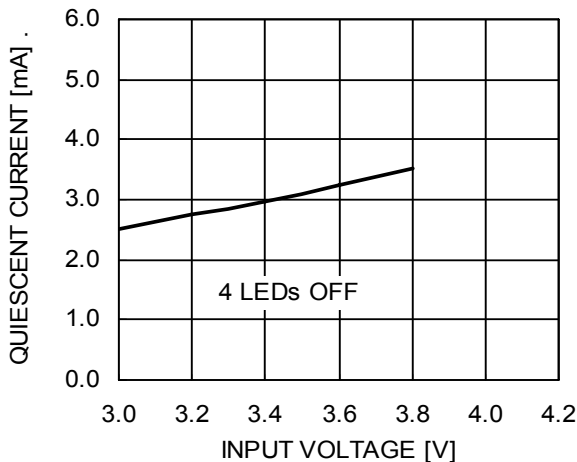
**Quiescent Current vs. Input Voltage (1x mode)**



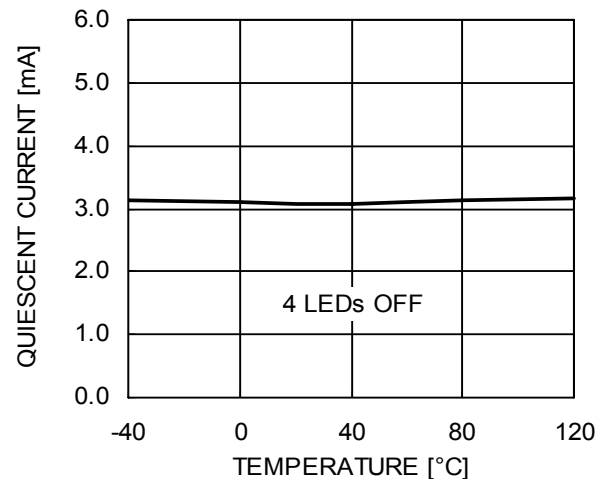
**Quiescent Current vs. Temperature (1x mode)**



**Quiescent Current vs. Input Voltage (1.5x mode)**



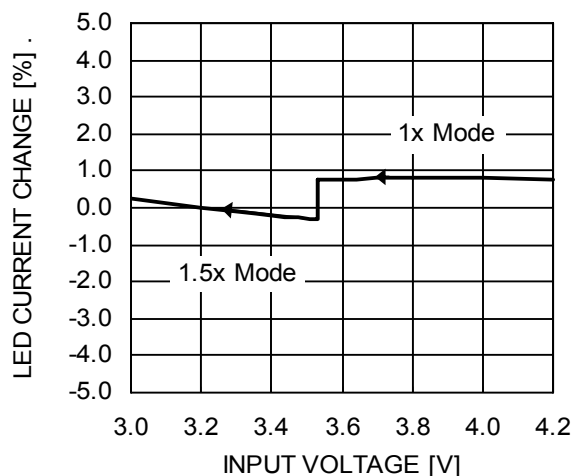
**Quiescent Current vs. Temperature (1.5x mode)**



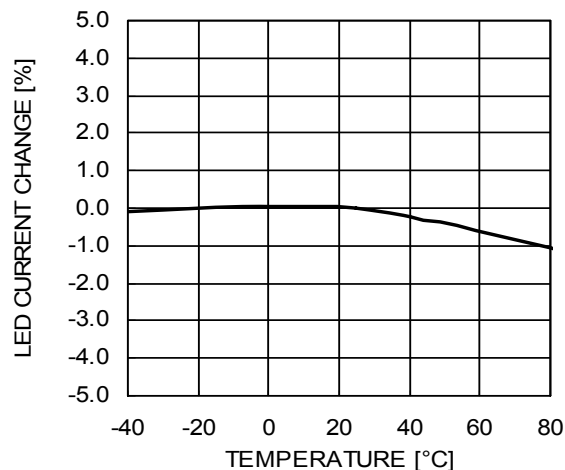
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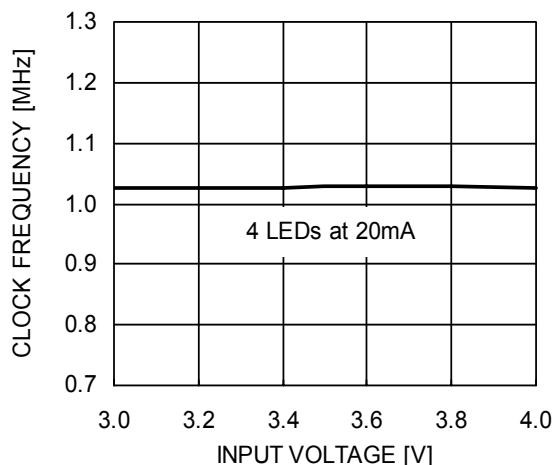
**LED Current Change vs. Input Voltage**



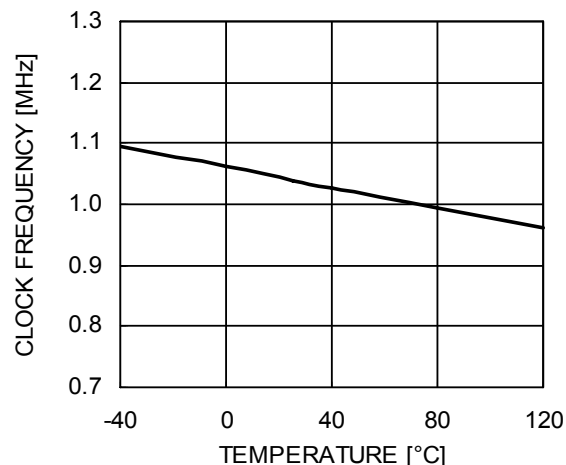
**LED Current Change vs. Temperature**



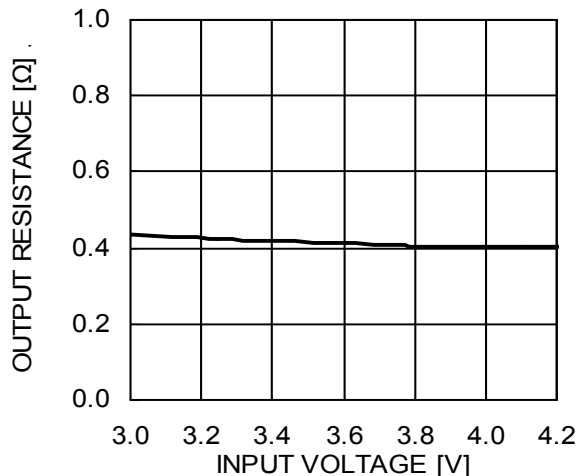
**Oscillator Frequency vs. Input Voltage**



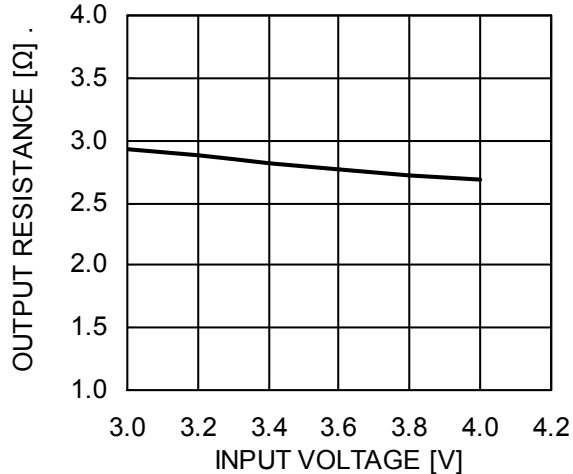
**Oscillator Frequency vs. Temperature**



**Output Resistance vs. Input Voltage (1x mode)**



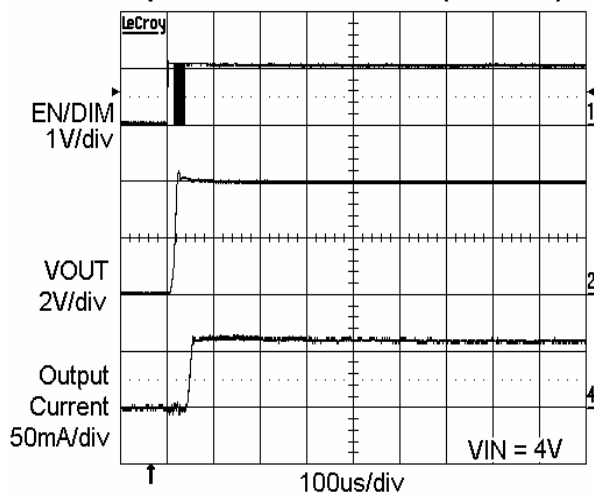
**Output Resistance vs. Input Voltage (1.5x mode)**



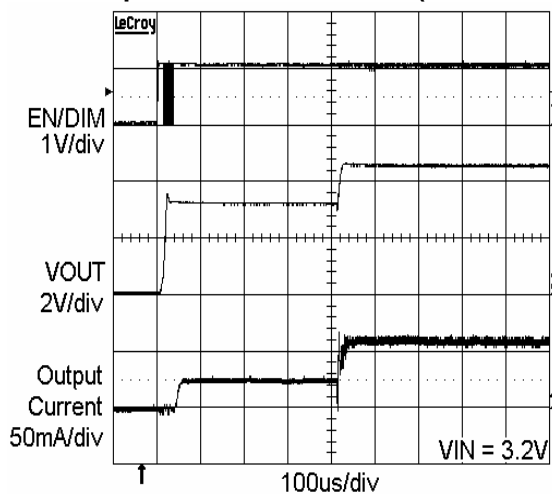
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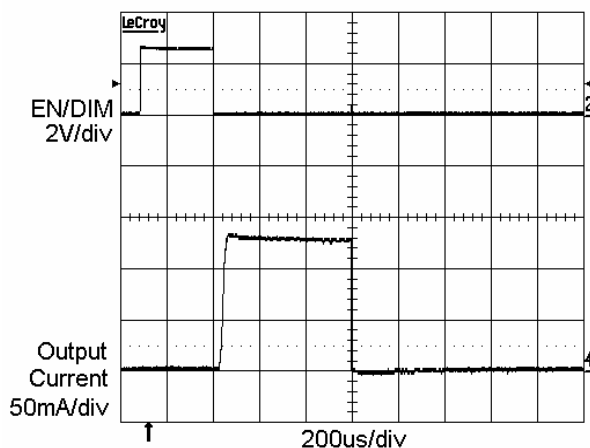
**Power Up with 4 LEDs at 15mA (1x Mode)**



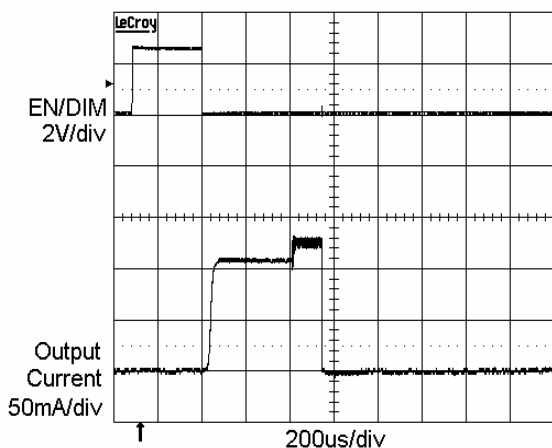
**Power Up with 4 LEDs at 15mA (1.5x Mode)**



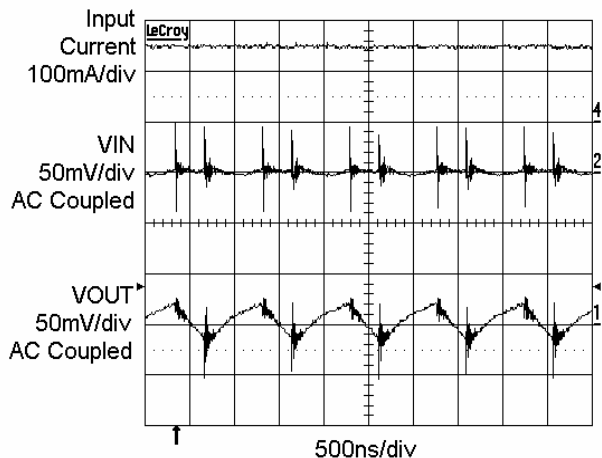
**Enable Power Down Delay (1x Mode)**



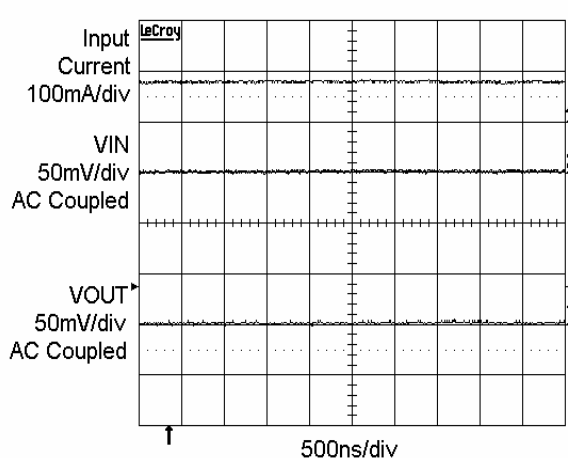
**Enable Power Down Delay (1.5x Mode)**



**Switching Waveforms in 1.5x Mode**



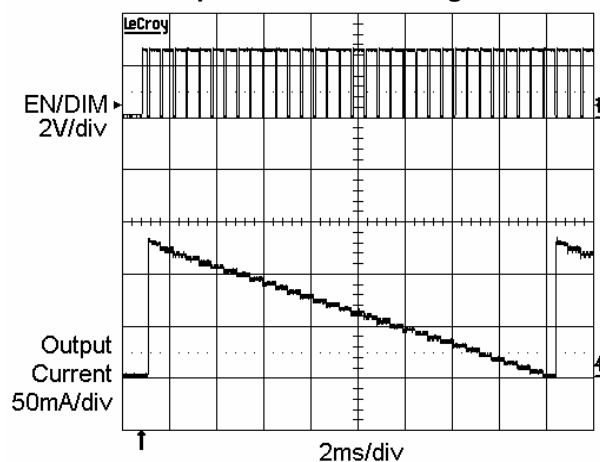
**Operating Waveforms in 1x Mode**



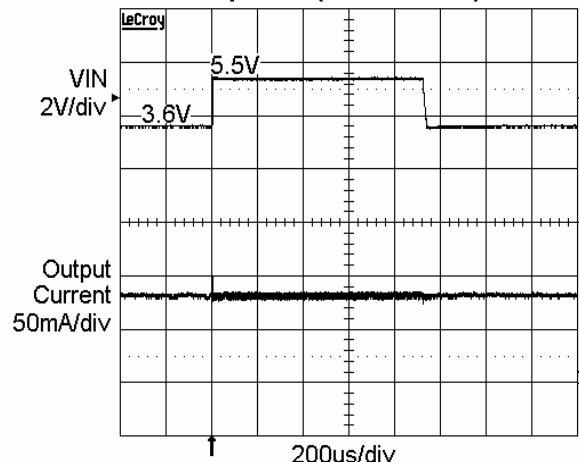
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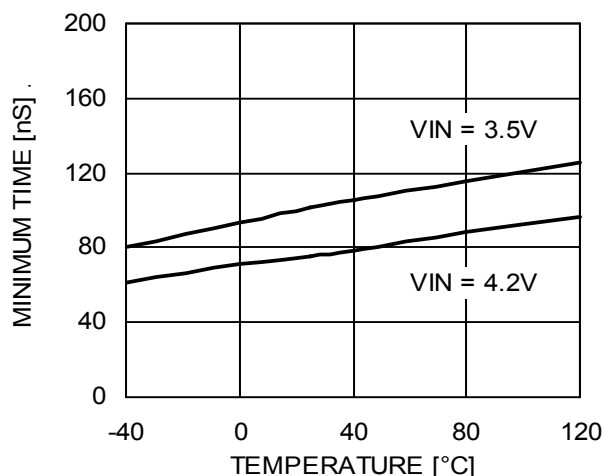
**Enable and Output Current Dimming Waveforms**



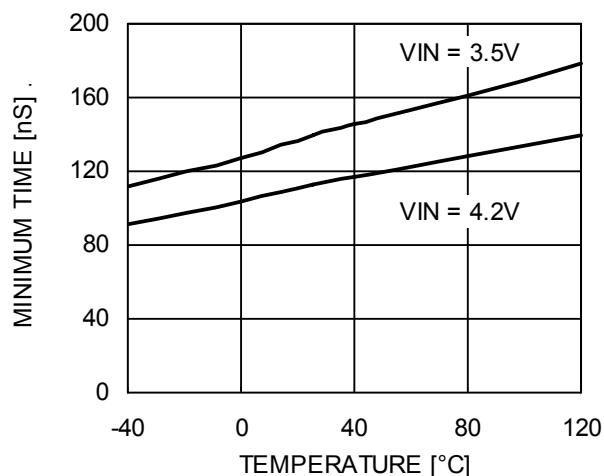
**Line Transient Response (3.6V to 5.5V) 1x Mode**



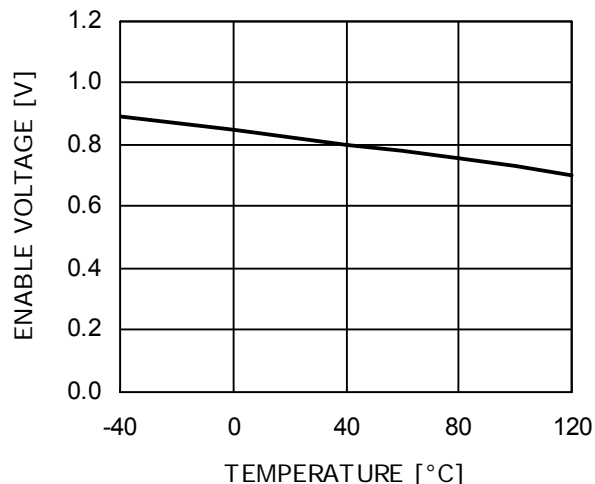
**Enable High Minimum Program Time vs. Temperature**



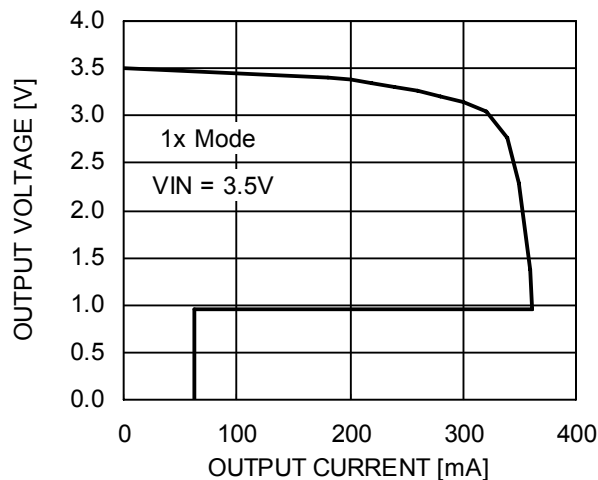
**Enable Low Minimum Program Time vs. Temperature**



**Enable Voltage Threshold vs. Temperature**



**Foldback Current Limit**



## PIN DESCRIPTIONS

Pin #	Name	Function
1	VIN	Supply voltage.
2	C1+	Bucket capacitor 1 terminal
3	C1-	Bucket capacitor 1 terminal
4	C2-	Bucket capacitor 2 terminal
5	C2+	Bucket capacitor 2 terminal
6	GND	Ground reference
7	LED1	LED1 cathode terminal (if not used, connect to VOUT) <sup>(1)</sup>
8	LED2	LED2 cathode terminal (if not used, connect to VOUT) <sup>(1)</sup>
9	LED3	LED3 cathode terminal (if not used, connect to VOUT) <sup>(1)</sup>
10	LED4	LED4 cathode terminal (if not used, connect to VOUT) <sup>(1)</sup>
11	EN/DIM	Device enable (active high) and dimming control input
12	VOUT	Charge pump output connected to the LED anodes
TAB	TAB	Connect to GND on the PCB

## PIN FUNCTION

**VIN** is the supply pin for the charge pump. A small 1 $\mu$ F ceramic bypass capacitor is required between the VIN pin and ground near the device. The operating input voltage range is from 2.2V to 5.5V. Whenever the input supply falls below the undervoltage threshold (2V) all LEDs channels will be automatically disabled.

**EN/DIM** is the enable and dimming control logic input for all LED channels. Guaranteed levels of logic high and logic low are set at 1.3V and 0.4V respectively. When EN/DIM is initially taken high, the device becomes enabled and all LED currents remain at 0mA. The falling edge of the first pulse applied to EN/DIM sets all LED currents to their full scale of 31mA.

On each consecutive falling edge of the pulse applied to EN/DIM, the LED current is decreased by 1mA step. On the 32nd pulse, the LED current is set to zero. The next pulse on EN/DIM resets the current back to their full scale of 31mA.

To place the device into zero current shutdown mode, the EN/DIM pin must be held low for 1.5ms or more.

**VOUT** is the charge pump output that is connected to the LED anodes. A small 1 $\mu$ F ceramic bypass capacitor is required between the VOUT pin and ground near the device.

**GND** is the ground reference for the charge pump. The pin must be connected to the ground plane on the PCB.

**C1+, C1-** are connected to each side of the 1 $\mu$ F ceramic bucket capacitor C1.

**C2+, C2-** are connected to each side of the 1 $\mu$ F ceramic bucket capacitor C2.

**LED1 to LED4** provide the internal regulated current for each of the LED cathodes. These pins enter a high impedance zero current state whenever the device is placed in shutdown mode. In applications using less than four LEDs, all unused channels should be wired directly to VOUT. This ensures the channel is automatically disabled dissipating less than 200 $\mu$ A.

**TAB** is the exposed pad underneath the package. For best thermal performance, the tab should be soldered to the PCB and connected to the ground plane.

### Notes:

(1) LED1, LED2, LED3, LED4 pins should not be left floating. They should be connected to the LED cathode, or tied to VOUT pin if not used.



Doc. No. MD-5035, Rev.B

## LED Current Setting

Figure 1 shows the timing diagram necessary at the EN/DIM input for setting the LED currents.

The EN/DIM set up time requires the signal to be held high for 10 $\mu$ s or longer to ensure the initialization of the driver at power-up. Each subsequent pulse on the EN/DIM (300ns to 200 $\mu$ s pulse duration) steps down the LED current from full scale of 31mA to zero with a 1mA resolution. Consecutive pulses should be separated by 300ns or longer. Pulsing beyond the 0mA level restores the current level back to full scale and the cycle repeats. Pulsing frequencies from 5kHz up to 1MHz can be supported during dimming operations. When the EN/DIM is held low for 1.5ms or more, the CAT3614 enters the shutdown mode and draws “zero” current.

For applications with three LEDs or less, any unused LED pins should be tied to VOUT, as shown on Figure 3.

## Protection Mode

If an LED becomes open-circuit, the output voltage VOUT is internally limited to about 5.5V. This is to prevent the output pin from exceeding its absolute maximum rating.

The driver enters a thermal shutdown mode as soon as the die temperature exceeds about +165°C. When the device temperature drops down by about 20°C, the device resumes normal operation.

## External Components

The driver requires a total of four external 1 $\mu$ F ceramic capacitors: two for decoupling input and output, and two for the charge pump. Both capacitor types X5R and X7R are recommended for the LED driver application. In the 1.5x charge pump mode, the input current ripple is kept very low by design, and an input bypass capacitor of 1 $\mu$ F is sufficient. In 1x mode, the device operating in linear mode does not introduce switching noise back onto the supply.

## Recommended Layout

In 1.5x charge pump mode, the driver switches internally at a high frequency of 1MHz. It is recommended to minimize trace length to all four capacitors. A ground plane should cover the area under the driver IC as well as the bypass capacitors. Short connection to ground on capacitors Cin and Cout can be implemented with the use of multiple vias. A copper area matching the TDFN exposed pad (GND) must be connected to the ground plane underneath. The use of multiple vias improves the package heat dissipation.

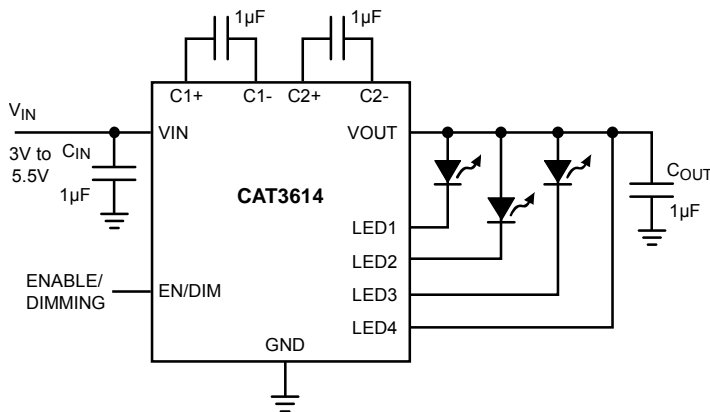


Figure 3. Three LED Application

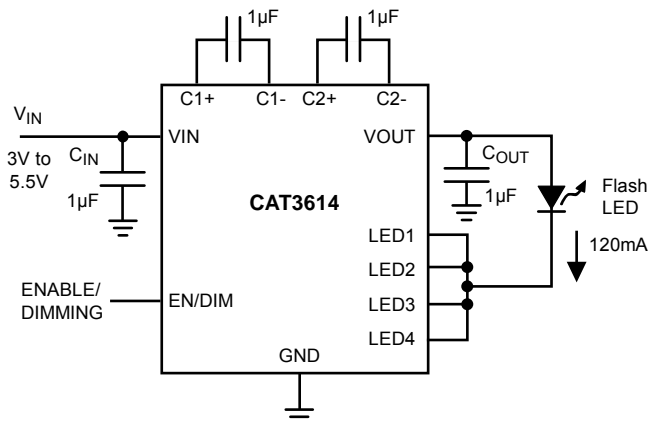
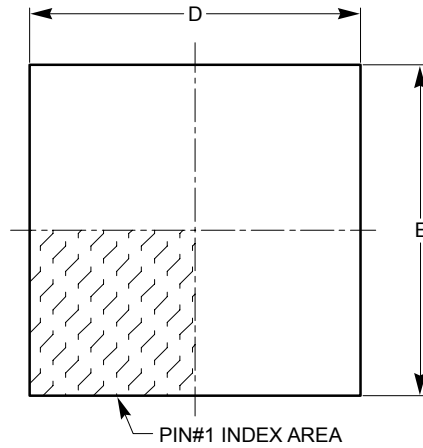


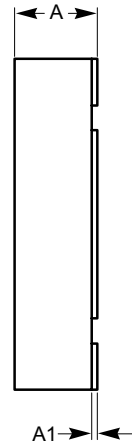
Figure 4. Single Flash LED Application

## PACKAGE OUTLINE DRAWING

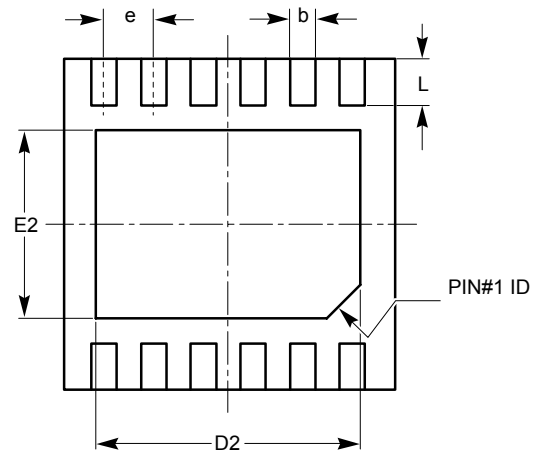
TDFN 12-Pad 3 x 3mm (HV2)<sup>(1)(2)</sup>



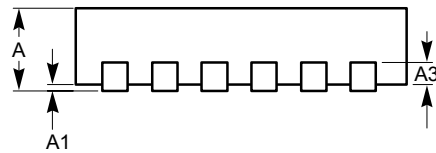
TOP VIEW



SIDE VIEW



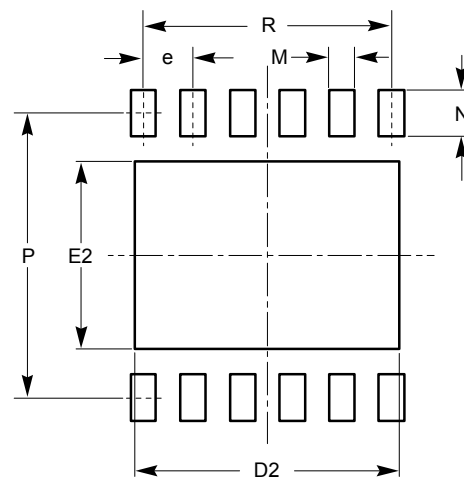
BOTTOM VIEW



FRONT VIEW

SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.178	0.203	0.228
b	0.18	0.23	0.30
D	2.90	3.00	3.10
D2	2.30	2.40	2.50
E	2.90	3.00	3.10
E2	1.55	1.70	1.75
e	0.45 BSC		
L	0.30	0.40	0.50
M	0.25	0.30	0.35
N	0.60	0.70	0.80
P	2.70	3.00	3.10
R	2.25 TYP		

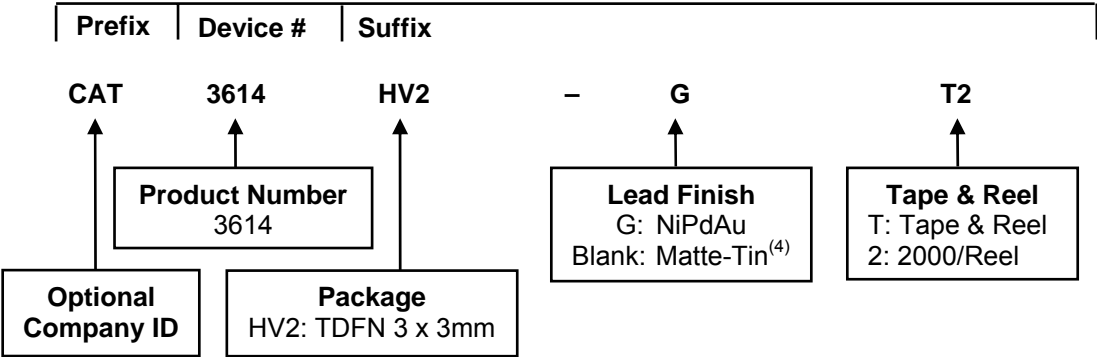
### RECOMMENDED LAND PATTERN



#### Notes:

- (1) All dimensions in millimeters.
- (2) Complies with JEDEC MO-229.

EXAMPLE OF ORDERING INFORMATION



**Notes:**

(1) All packages are RoHS-compliant (Lead-free, Halogen-free).

(2) The standard lead finish is NiPdAu.

(3) The device used in the above example is a CAT3614HV2-GT2 (TDFN, NiPdAu Plated Finish, Tape & Reel 2000).

(4) For additional package, please contact your nearest Catalyst Semiconductor Sales office.

## REVISION HISTORY

Date	Rev.	Reason
02/09/2006	00	Initial Release
07/21/2006	01	Update Typical Application Circuit Update Pin Descriptions Update Electrical Operating Characteristics
01/07/08	B	Add NiPdAu lead finish. Add Extended Temperature Range. Update Package Outline Drawing. Add Example of Ordering Information. Change document number from 25095 to MD-5035.

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